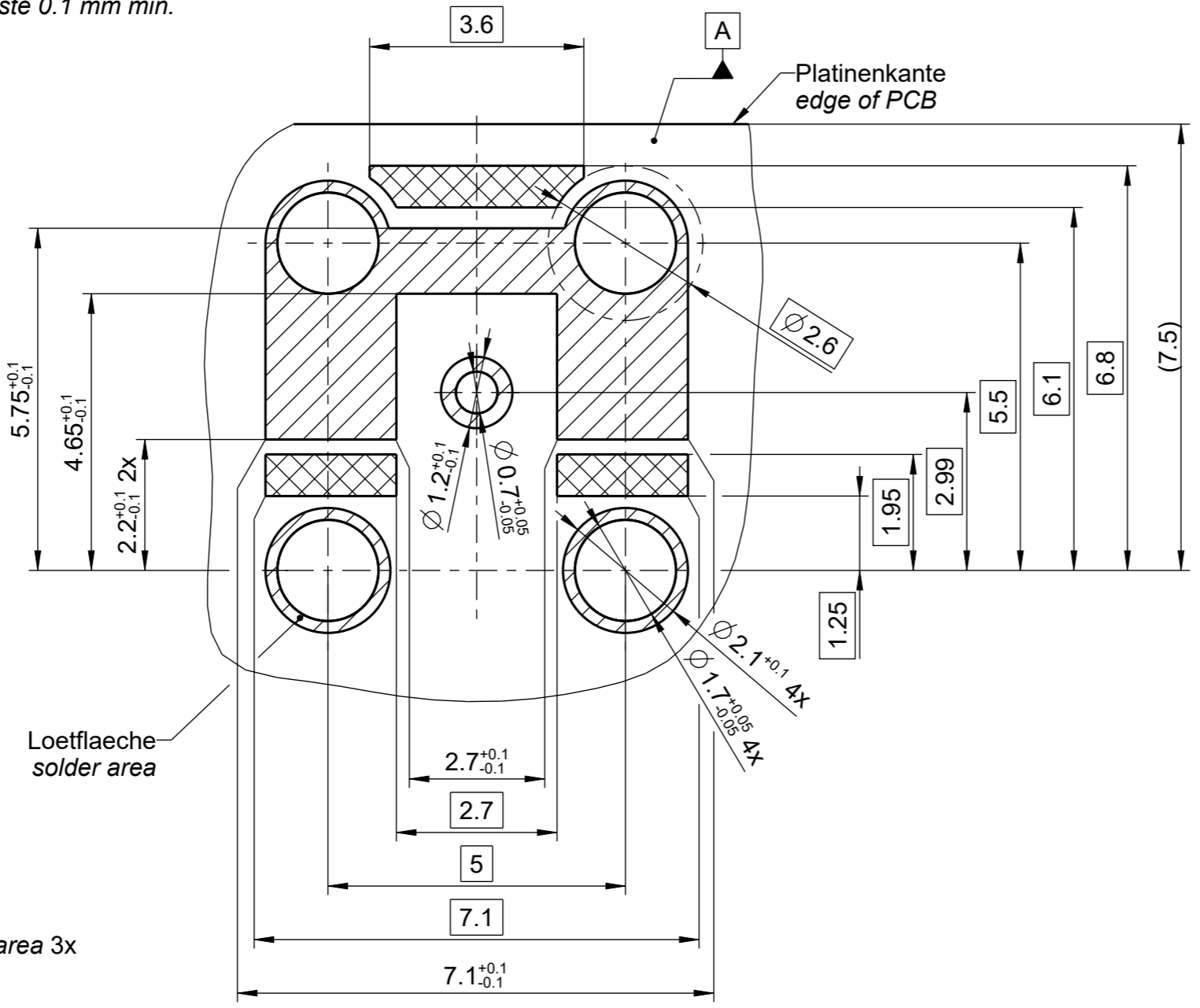




- 1) Alle Bohrungen durchkontaktieren mit Restringen auf Rückseite.  
 (Restringbreite min. 0.2mm)  
*All drill holes plated inclusive pads on the backside.  
 (padwidth min. 0.2mm)*
- 2) Lötpastenhöhe 0.1 mm min.  
*Thickness of soldering paste 0.1 mm min.*



-  Lötfläche / solder area 3x
-  Auflagefläche, frei von Lot / stand off area, free of solder 3x

Die angegebenen Maße und Toleranzen sind nur Empfehlungen  
*The stated dimension are only recommendations*

*A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.*

*Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimal solderability of the connector.*

*In order to guarantee optimal high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.*

alle Bohrungen / all drill holes  $\text{⌀} \begin{matrix} 5x \\ \oplus \\ \text{⌀} 0.05 \text{ (M)} \\ \text{A} \end{matrix}$

<b>Rosenberger</b>		general tolerance		scale: 10:1 ( )	weight[g]: ---
		ISO 2768 mH	RN 006-01	surface[mm <sup>2</sup> ]: ---	
vertraulich / confidential		date	name	title: <b>Leiterplatten-Layout PCB layout</b>	
		drawn	03.08.2016 C_Schmidt		
		check	17.05.2022 B_Krammer		
rev.	change-no	name	date	drawing-no.: MB_603	sheet: 1
dimensioning incl. plating				of: 1	remarks: .
Size ISO 14405 (E) Tolerancing ISO 8015					